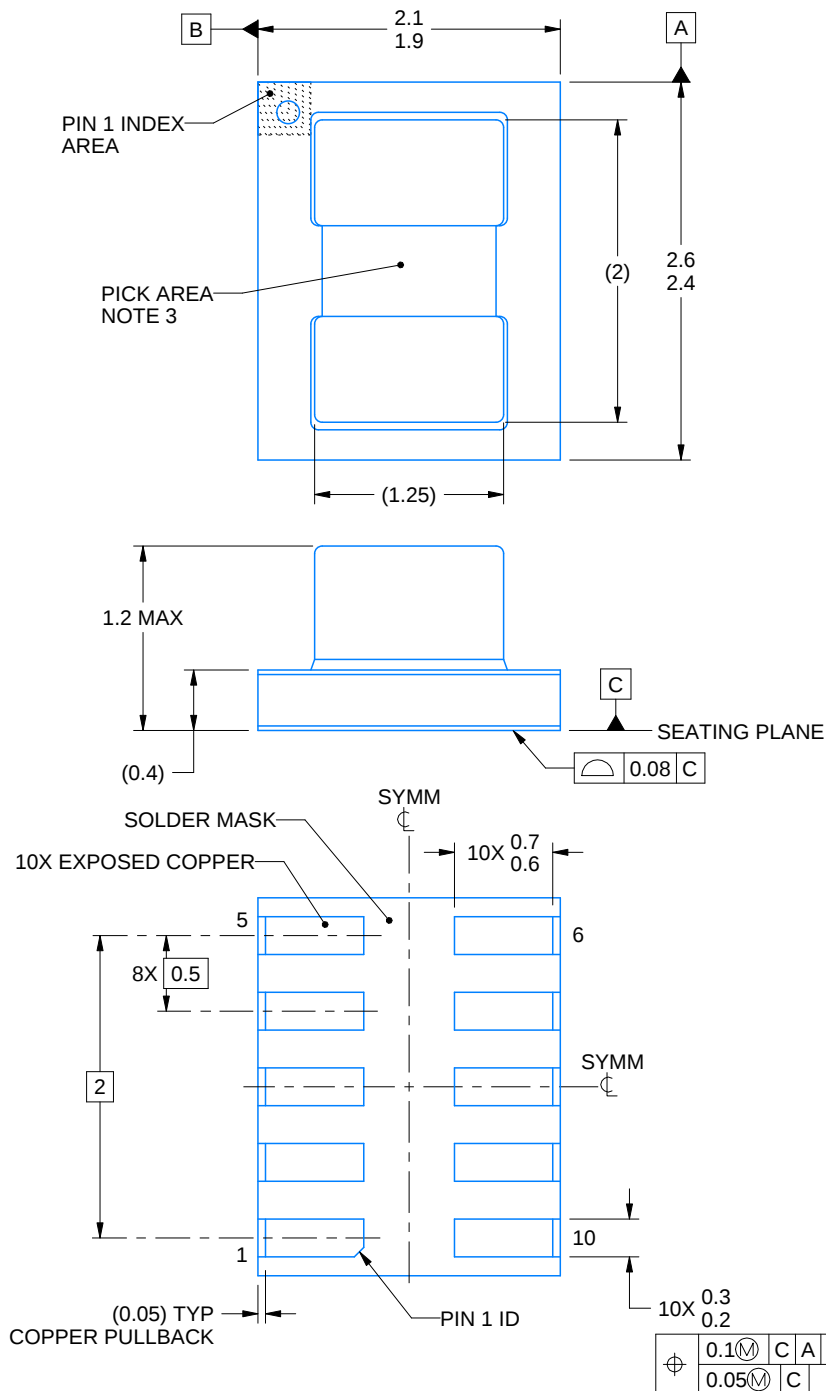
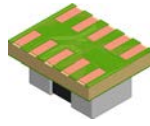




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NOTES:

MicroSiP is a trademark of Texas Instruments

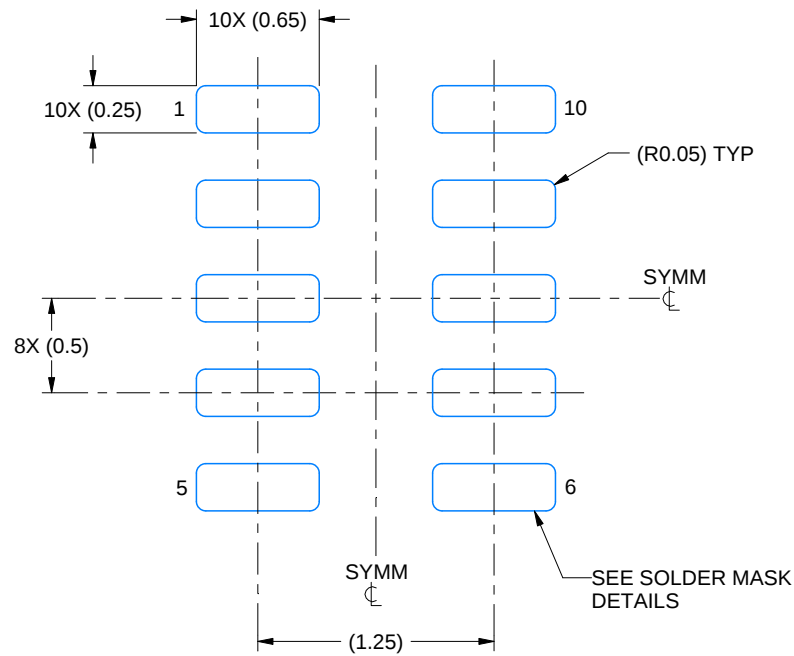
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Pick and place nozzle $\varnothing$ 0.33 mm or smaller recommended.

EXAMPLE BOARD LAYOUT

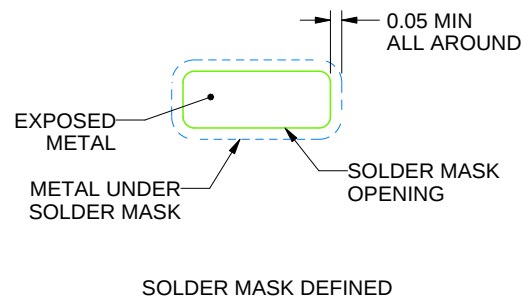
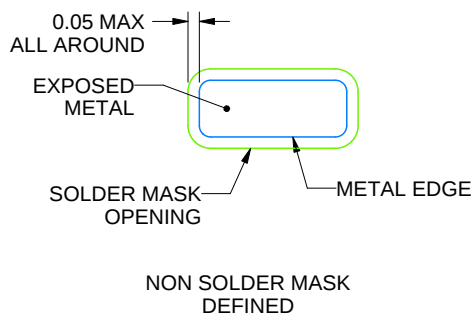
SIH0010A

uSIP™ - 1.2 mm max height

MICRO SYSTEM IN PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:25X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

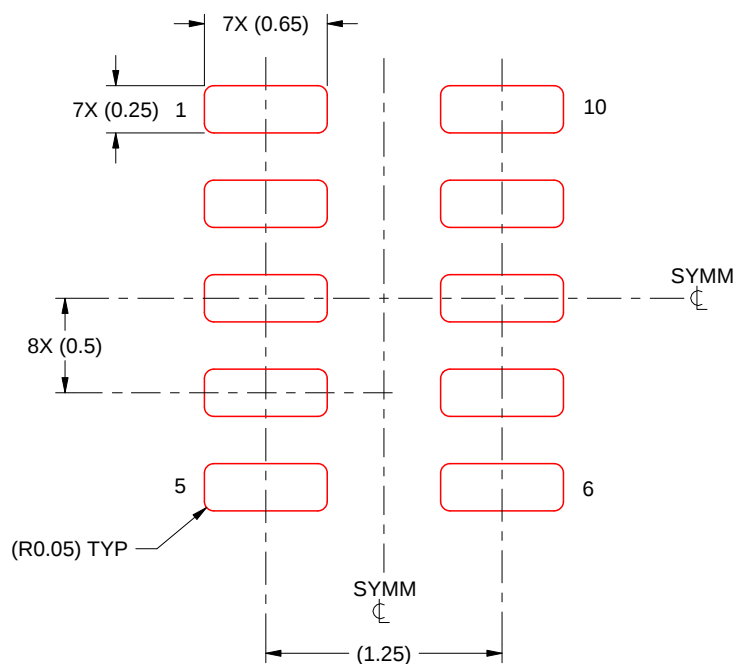
4. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).

EXAMPLE STENCIL DESIGN

SIH0010A

uSIP™ - 1.2 mm max height

MICRO SYSTEM IN PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:25X

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NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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